

### 華泰電子股份有限公司

Orient Semiconductor Electronics, Ltd.

(股票代號:2329)

# 2024年法人說明會 INVESTOR CONFERENCE

14 JUN, 2024



## Summary

- Part 1 Company Profile
- Part 2 Manufacture Service & Product
- Part 3 2024 Q1 Financial Performance
- Part 4 Competitive Advantage
- Part 5 Q&A





## **Company Profile**





## **Company History**



>> 資本額 Capital: US\$ 235M(NTD7.35B)

Common Stock : US\$ 178M(NTD5.55B) Preferred C Stock : US\$ 57M(NTD1.80B) 2024

**53th Anniversary Celebration** 

2015 & 2020

**Strategic Partnership Announcement** 

2014

1st 16D microSD in the world

2005

**Biz Transformation into Memory Market** 

2000

**HQ Building Officially Opened** 

Apr, 1994

IPO in Taiwan Stock Exchange (TSE: 2329)

1971 Established

Founder: Dr. Eugene C. Y. Duh

Headquarters: Kaohsiung, Taiwan



### **Factory**



- >> 6 Production buildings in NTIP
- >> Headcount : around 5,200



Facility 2 (59,223 sq. ft.)







Facility 3 (158,638 sq. ft.)





Facility 5 (190,000 sq. ft.)

Facility 1 (146,475 sq ft.)



## Organization

Chairman
Tony Tung

President
C. J. Tu

**Testing Group Terry Lin** 

- Memory IC Testing Service
- Logic IC Testing Service

Semiconductor Group M. L. Tsai

- Memory IC Packaging Service
- Logic IC Packaging Service

EMS Group Major Lee

EMS Service



# Manufacture Service & Product





#### **Total Solution**



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主動創新 INNOVATION 積極用心 PROACTIVENESS

### **Total Solution**

#### >>> Electronics Manufacturing Service



**Product Design** from Customer



JDM, DFM, DFT



NPI & Quick Turn Prototyping



Material Procurement





Repair and Upgrade



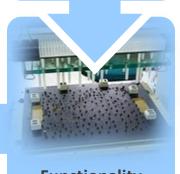
**Distribution Support** 



System Integration



**Box Build** 



Functionality & Reliability Testing



## **Product & Application**



**Memory** 

Consumer Electronics

Industrial

Automotive

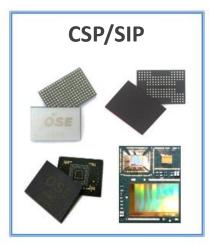
Aerospace

Communication











<sup>\*</sup>Includes Wire Bond Type, Flip Chip Type, SiP, etc



# 2024 Q1 Financial Performance





# CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME (QoQ)

(Thousands of NTD)	Q1/2024	%	Q4/2023	%	Variance
Net revenue	4,176,029	100.00%	4,736,282	100.00%	(11.83%)
Gross profit	826,627	19.79%	1,189,929	25.12%	(30.53%)
Operating income	518,217	12.41%	845,507	17.85%	(38.71%)
Income before tax	622,033	14.90%	754,941	15.94%	(17.61%)
Income tax(expense)	(122,684)	(2.94%)	(154,511)	(3.26%)	(20.60%)
Non controlling interests	-	-	-	-	-
Net Income	499,349	11.96%	600,430	12.68%	(16.83%)
Basic EPS (in NTD)	0.70	-	0.86	-	-
EBITDA	843,720	20.20%	988,705	20.88%	(14.66%)

誠正信實 INTEGRITY 主動創新 INNOVATION 積極用心 PROACTIVENESS



# CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME (YoY)

(Thousands of NTD)	Q1/2024	%	Q1/2023	%	Variance
Net revenue	4,176,029	100.00%	3,253,411	100.00%	28.36%
Gross profit	826,627	19.79%	321,407	9.88%	157.19%
Operating income (loss)	518,217	12.41%	101,004	3.10%	413.07%
Income (loss) before tax	622,033	14.90%	97,749	3.00%	536.36%
Income tax (expense) gains	(122,684)	(2.94%)	81,972	2.52%	(249.67%)
Non controlling interests	-	-	-	-	-
Net Income	499,349	11.96%	179,721	5.52%	177.85%
Basic EPS (in NTD)	0.70	-	0.25	-	180.00%
EBITDA	843,720	20.20%	375,060	11.53%	124.96%

誠正信實 INTEGRITY

主動創新 INNOVATION 積極用心 PROACTIVENESS



### **Key Items & Index of Balance Sheet**

(Thousands of NTD)	Q1/2024	Q4/2023	Variance
Cash and cash equivalents	4,281,821	3,909,728	9.52%
Financial assets measured at amortized cost	-	-	-
Financial assets-Noncurrent & Investments-equity method	2,055,652	1,839,213	11.77%
Property, plant, and equipment	5,370,723	5,081,550	5.69%
Total assets	19,259,288	18,467,008	4.29%
Short-term loans & Short-term notes payable	-	-	_
Long-Term Liabilities-Current Portion	181,555	107,054	69.59%
Long-term loans	1,104,503	1,131,908	(2.42%)
Total liabilities	8,187,583	7,193,165	13.82%
Total stockholders' equity	11,071,705	11,273,843	(1.79%)
Quarterly EBITDA	843,720	988,705	(14.66%)
Index			
Debt ratio	42.51%	38.95%	
Accounts receivable turnover days(Q1)	99Days	85Days	
Inventory turnover days(Q1)	43Days	41Days	

誠正信實 INTEGRITY 主動創新 INNOVATION 積極用心 PROACTIVENESS



### **Key Items & Index of Balance Sheet**

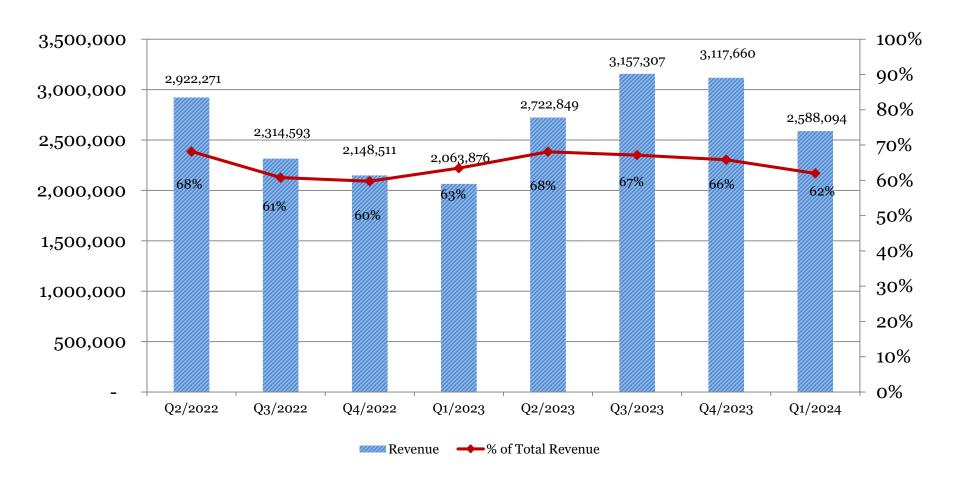
(Thousands of NTD)	Q1/2024	Q1/2023	Variance
Cash and cash equivalents	4,281,821	3,292,177	30.06%
Financial assets measured at amortized cost	-	-	-
Financial assets-Noncurrent & Investments-equity method	2,055,652	1,313,702	56.48%
Property, plant, and equipment	5,370,723	5,128,296	4.73%
Total assets	19,259,288	16,191,118	18.95%
Short-term loans & Short-term notes payable	-	_	_
Long-Term Liabilities-Current Portion	181,555	2,904	6,151.89%
Long-term loans	1,104,503	1.146,058	(3.63%)
Total liabilities	8,187,583	6,043,678	35.47%
Total stockholders' equity	11,071,705	10,147,440	9.11%
Quarterly EBITDA	843,720	375,060	124.96%
Index			
Debt ratio	42.51%	37.33%	
Accounts receivable turnover days(Q1)	99Days	84Days	
Inventory turnover days(Q1)	43Days	52Days	

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### **IC Packaging and Testing Services**

(Thousands of NTD)

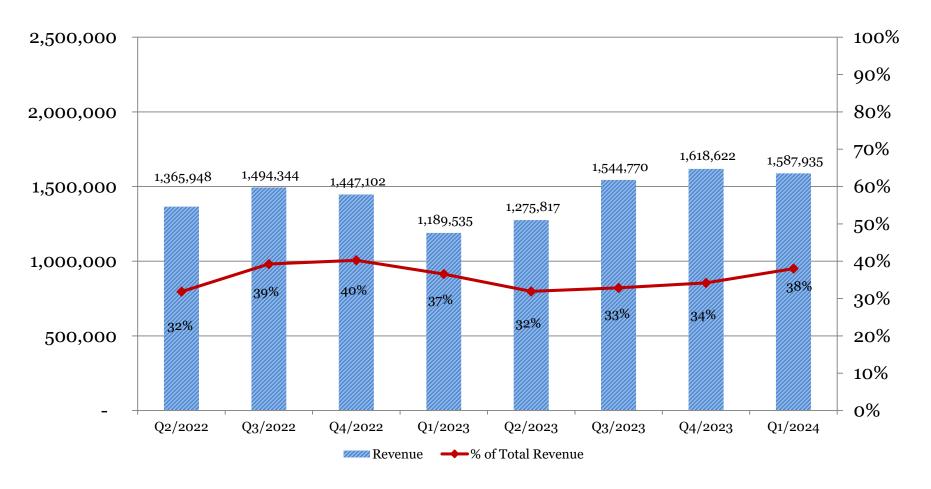






### **Electronics Manufacturing Services**

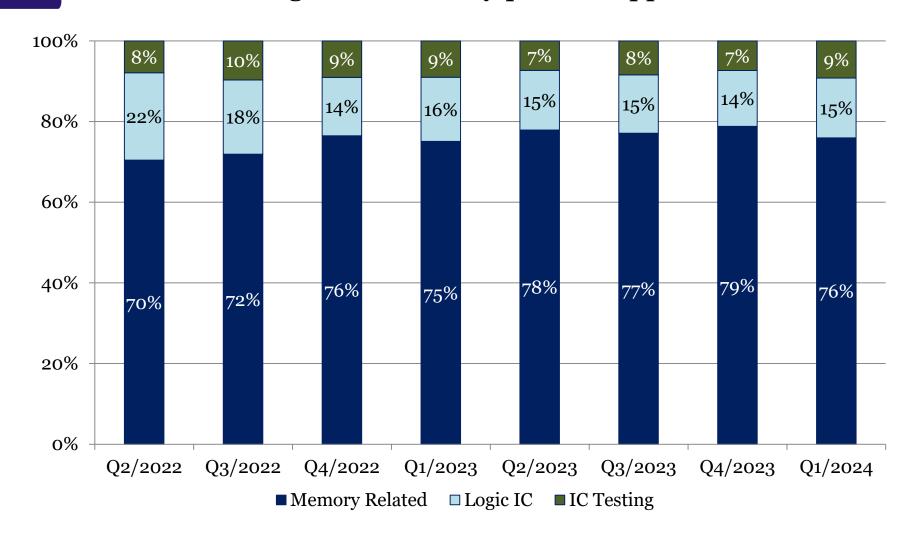
(Thousands of NTD)





### **Semiconductor Group**

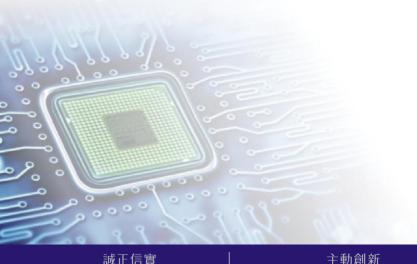
-Percentage of revenue by product application







# Competitive Advantage







- Capable of both IC & EMS / One-Stop Service.
- Sufficient experience with worldclass customers working with us.



- Advanced Process Capability
  - 25um wafer thickness
  - 16 Layers Die Stacking for micro SD/BGA/SD
  - Sip / Flip Chip / Wire Bond / Module Availability
  - -High-end Technology



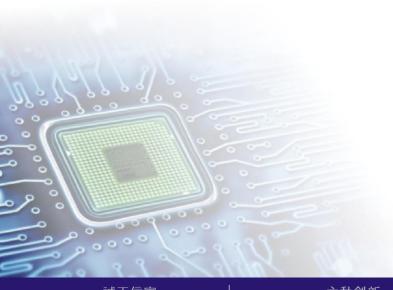
- Digitalization
- MES Automation System



- Customer Oriented & Customization
- High Degree of Flexibility on capacity allocation



## Q&A



integrity 主動創新 innovation



### Disclaimer

The presentation and the relevant information mentioned in this material have been compiled from both internal and external resources.

These forward looking statements involve known and unknown risks, uncertainties and other factors, including price variation, competition, global economy, exchange rate movement and market demand, which may cause actual results to differ materially from those implied by such forward-looking statements.

The forward looking statements expressed in this material reflect the Company's current view about the future as of today. The Company is not responsible for any updates if there are any changes in the future.